
Guest editorial

The International Microelectronics and Packaging Society (IMAPS) Poland Chapter was established in September 1982. In the beginning, it was the ISHM-Poland Chapter and from 1997 it became the IMAPS-Poland Chapter.

The IMAPS is a non-profit-making organization whose aim is to spread of knowledge relating to hybrid microelectronics, a key technology in the assembly and application of semiconductors, thin film circuits and printed circuit boards (PCBs) to form practical miniaturized electronic equipment. In 2008, the IMAPS joined with IEEE Components, Packaging and Manufacturing Technology (CPMT) Society, bringing into formation the IMAPS-CPMT organization.

The 40th IMAPS Poland International Conference was held in Wałbrzych in Książ Castle and took place between September 25 to 28, 2016. This event was organized by the Wrocław University of Science and Technology. The scope of the Conference covered everything in electronics between the chip and the system. The conference was attended by 93 participants, including 16 guests from abroad. During the Conference, 18 invited lectures and 63 posters were presented. The conference was supported by six international journals indexed in Journal Citation Report database and one domestic journal.

This year, as in the previous year, two young scientists have been awarded winning the refund of the conference fee during the next IMAPS 2017 Poland Conference.

Also two awards for women in science have been given by Visegrad International Network for Microelectronics Engineering Scientists (VINmes).

In this special issue of *Microelectronics International*, nine papers have been selected from the conference. All of them were subjected to the journal's regular reviewing procedure.

Four papers are related to LTCC (Low Temperature Cofired Ceramics) technology (Synkiewicz *et al.*, Kulawik *et al.*, Belavič, Pietrikova *et al.*).

Next papers by Magonski and Dziurdzia and Gierczak *et al.* describe different electronic structures fabrications.

The first paper of Filipowski *et al.* treats about the influence of spray-on glass solution on fabrication of emitter layer in silicon solar cells. Their second paper is about the relationship between resistance, TCR and stabilization temperature of amorphous Ni-P alloy.

In the last one paper (by Górecki and Górecki) presents the modeling dynamic characteristics of the Insulated Gate Bipolar Transistors.

I would like to thank all the authors for their scientific work and contributions that have led to the development and publication of this special issue of *Microelectronics International*. I hope that it will be of interest to readers of the journal and that it will help them to find novel solutions, contribute to the creation of new ideas and initiate many varied discussions about the technologies in microelectronics. I believe that this branch of science could be effectively developed in the future.

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